

L Number	Hits	Search Text	DB	Time stamp
-	193	349/150.ccls.	USPAT	2003/12/14 18:28
-	419	349/149.ccls.	USPAT	2003/12/14 17:59
-	145	349/151.ccls.	USPAT	2003/12/14 18:04
-	230	349/152.ccls.	USPAT	2003/12/14 18:11
-	123	349/149-152.ccls. and (multilayer\$ or multi-layer\$ or "multi layer" or "multi layered")	USPAT	2003/12/14 18:12
-	23	349/149-152.ccls. and (multilayer\$ or multi-layer\$ or "multi layer" or "multi layered") with flexible	USPAT	2003/12/14 18:12
-	4778	g02f001/1345	JPO	2003/12/14 18:57
-	64	g02f001/1345 and (multi-layer\$ or multilayer\$)	JPO	2003/12/14 19:03
-	185	g02f001/1345 and dummy	JPO	2003/12/14 18:31
-	35	g02f001/1345 and dummy with conductive	JPO	2003/12/14 18:31
-	11	g02f001/1345 and dummy with conductive with pattern	JPO	2003/12/14 18:33
-	8	g02f001/1345 and "stress concentration"	JPO	2003/12/14 18:37
-	53	g02f001/1345 and "flexible printed circuit board"	JPO	2003/12/14 18:38
-	15	g02f001/1345 and flexible and "input terminal" and "output terminal"	JPO	2003/12/14 18:39
-	44	g02f001/1345 and flexible and "connection terminal"	JPO	2003/12/14 18:39
-	1	g02f001/1345 and trunk and branch	JPO	2003/12/14 18:40
-	20	g02f001/1345 and "conductive layers"	JPO	2003/12/14 18:40
-	1	g02f001/1345 and "conductive layers" and dummy	JPO	2003/12/14 18:46
-	16	g02f001/1345 and plurality with group\$ with terminal\$	JPO	2003/12/14 18:49
-	60	g02f001/1345 and "compression bonding"	JPO	2003/12/14 18:52
-	801	g02f001/1345 and seiko.as.	JPO	2003/12/14 18:57
-	449	g02f001/1345 and hitachi.as.	JPO	2003/12/14 18:57
-	1	g02f001/1345 and hitachi.as. and yamazaki.in. and hiroyuki.in.	JPO	2003/12/14 18:58
-	9	g02f001/1345 and hitachi.as. and kawamura.in. and tetsuya.in.	JPO	2003/12/14 18:59
-	1	JP02003100737A	JPO	2003/12/14 19:03